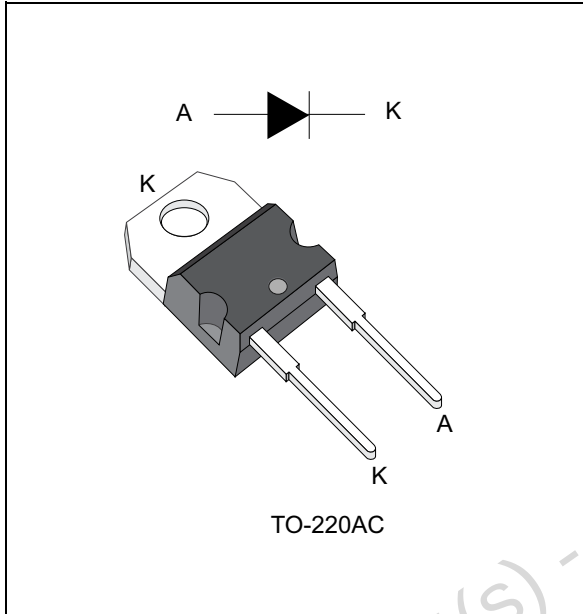




Description

The STPS30M60 is a single diode Schottky rectifier, suited for high frequency switch mode power supply.

Packaged in TO-220AC, this device is intended to be used in notebook, game station and desktop adapters, providing in these applications a good efficiency at both low and high load.

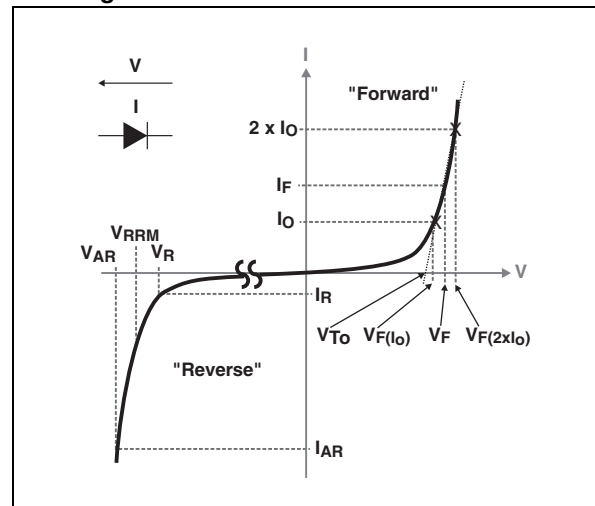
Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	30 A
V_{RRM}	60 V
T_j (max)	150 °C
V_F (typ)	0.385 V

Features

- High current capability
- Avalanche rated
- Low forward voltage drop
- High frequency operation

Figure 1. Electrical characteristics(a)



- a. V_{ARM} and I_{ARM} must respect the reverse safe operating area defined in Figure 9. V_{AR} and I_{AR} are pulse measurements ($t_p < 1 \mu s$). V_R , I_R , V_{RRM} and V_F , are static characteristics

1 Characteristics

Table 2. Absolute ratings (limiting values at $T_{amb} = 25\text{ °C}$, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		60	V
$I_{F(RMS)}$	Forward rms current		60	A
$I_{F(AV)}$	Average forward current, $\delta = 0.5$	$T_c = 130\text{ °C}$	30	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms sine-wave}$	450	A
$P_{ARM}^{(1)}$	Repetitive peak avalanche power	$T_j = 125\text{ °C}$, $t_p = 10\text{ }\mu\text{s}$	2470	W
$V_{ARM}^{(2)}$	Maximum repetitive peak avalanche voltage	$t_p < 1\text{ }\mu\text{s}$, $T_j < 150\text{ °C}$, $I_{AR} < 129$	80	V
$V_{ASM}^{(2)}$	Maximum single-pulse peak avalanche voltage	$t_p < 1\text{ }\mu\text{s}$, $T_j < 150\text{ °C}$, $I_{AR} < 129$	80	V
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature ⁽³⁾		150	°C

- For pulse time duration deratings, please refer to [Figure 4](#). More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the STMicroelectronics Application notes AN1768, "Admissible avalanche power of Schottky diodes" and AN2025, "Converter improvement using Schottky rectifier avalanche specification".
- See [Figure 9](#)
- $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	0.9	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	35	165	μA
		$T_j = 125\text{ °C}$		-	25	100	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 15\text{ A}$	-	0.480	0.520	V
		$T_j = 125\text{ °C}$		-	0.385	0.435	
		$T_j = 25\text{ °C}$	$I_F = 30\text{ A}$	-	0.545	0.605	
		$T_j = 125\text{ °C}$		-	0.480	0.550	

- Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$
- Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.39 \times I_{F(AV)} + 0.0053 \times I_{F(RMS)}^2$$

Figure 2. Average forward power dissipation versus average forward current

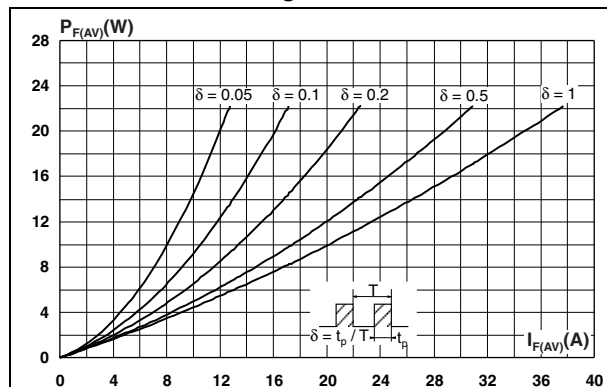
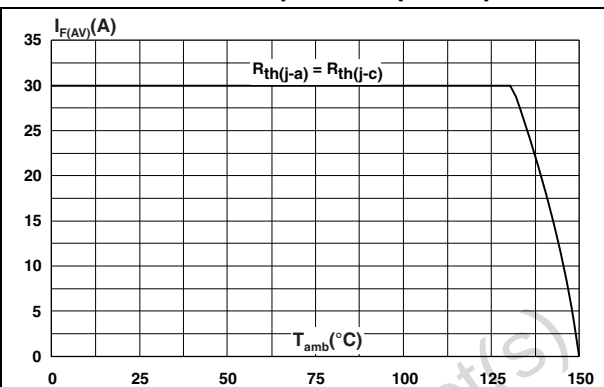
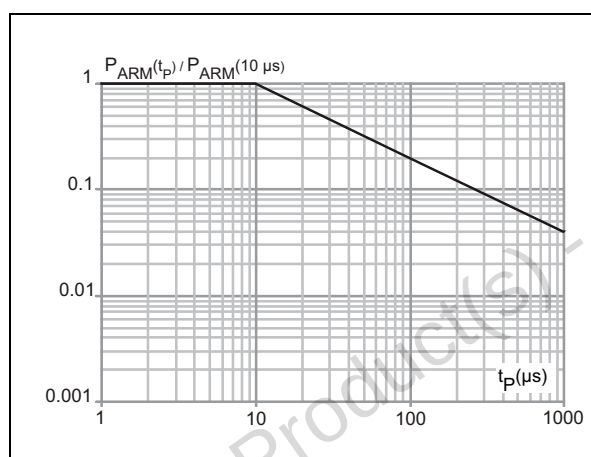
Figure 3. Average forward current versus ambient temperature ($\delta = 0.5$)Figure 4. Normalized avalanche power derating versus pulse duration ($T_j = 125^\circ\text{C}$)

Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

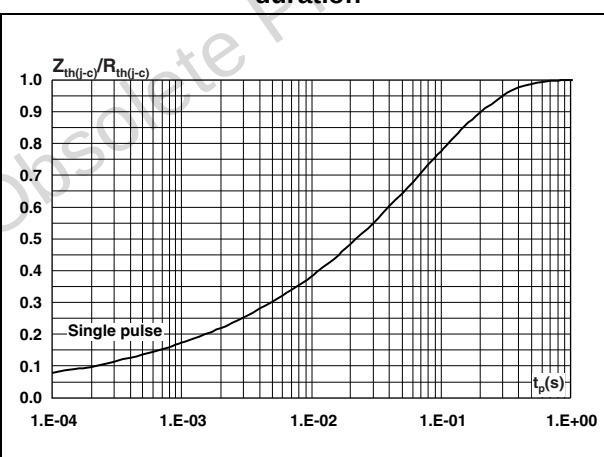


Figure 6. Reverse leakage current versus reverse voltage applied (typical values)

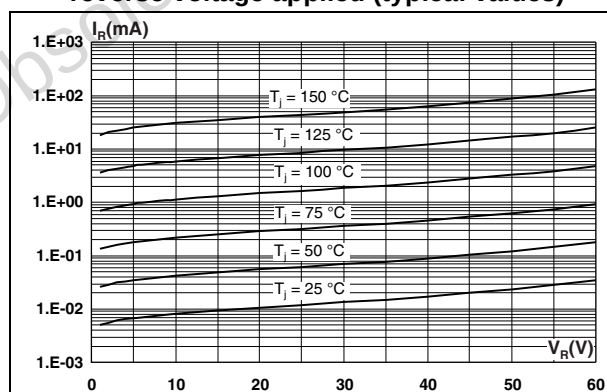


Figure 7. Junction capacitance versus reverse voltage applied (typical values)

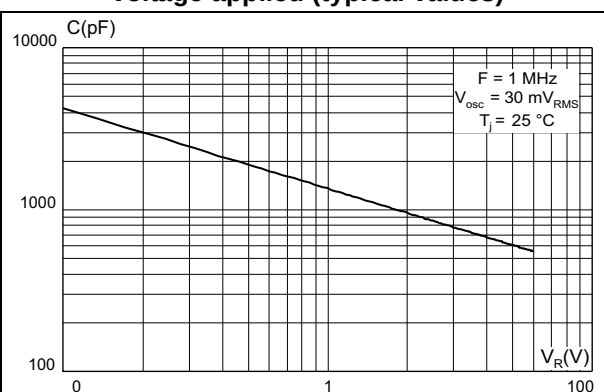


Figure 8. Forward voltage drop versus forward current

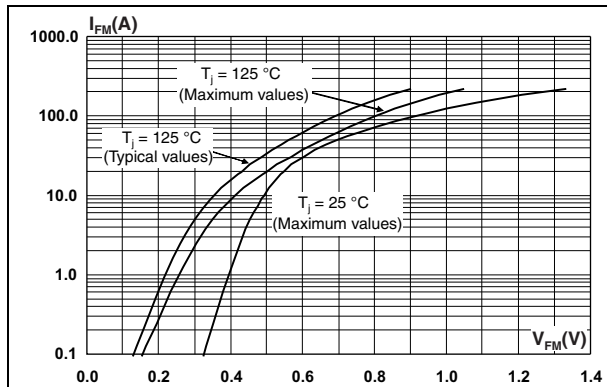
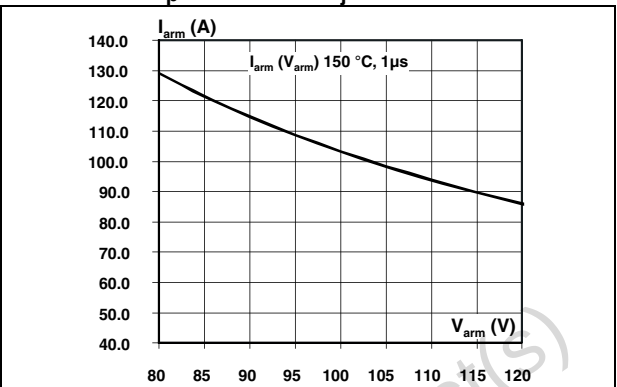


Figure 9. Reverse safe operating area ($t_p < 1\text{ }\mu\text{s}$ and $T_j < 150\text{ °C}$)



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.7 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 TO-220AC package information

Figure 10. TO-220AC package outline

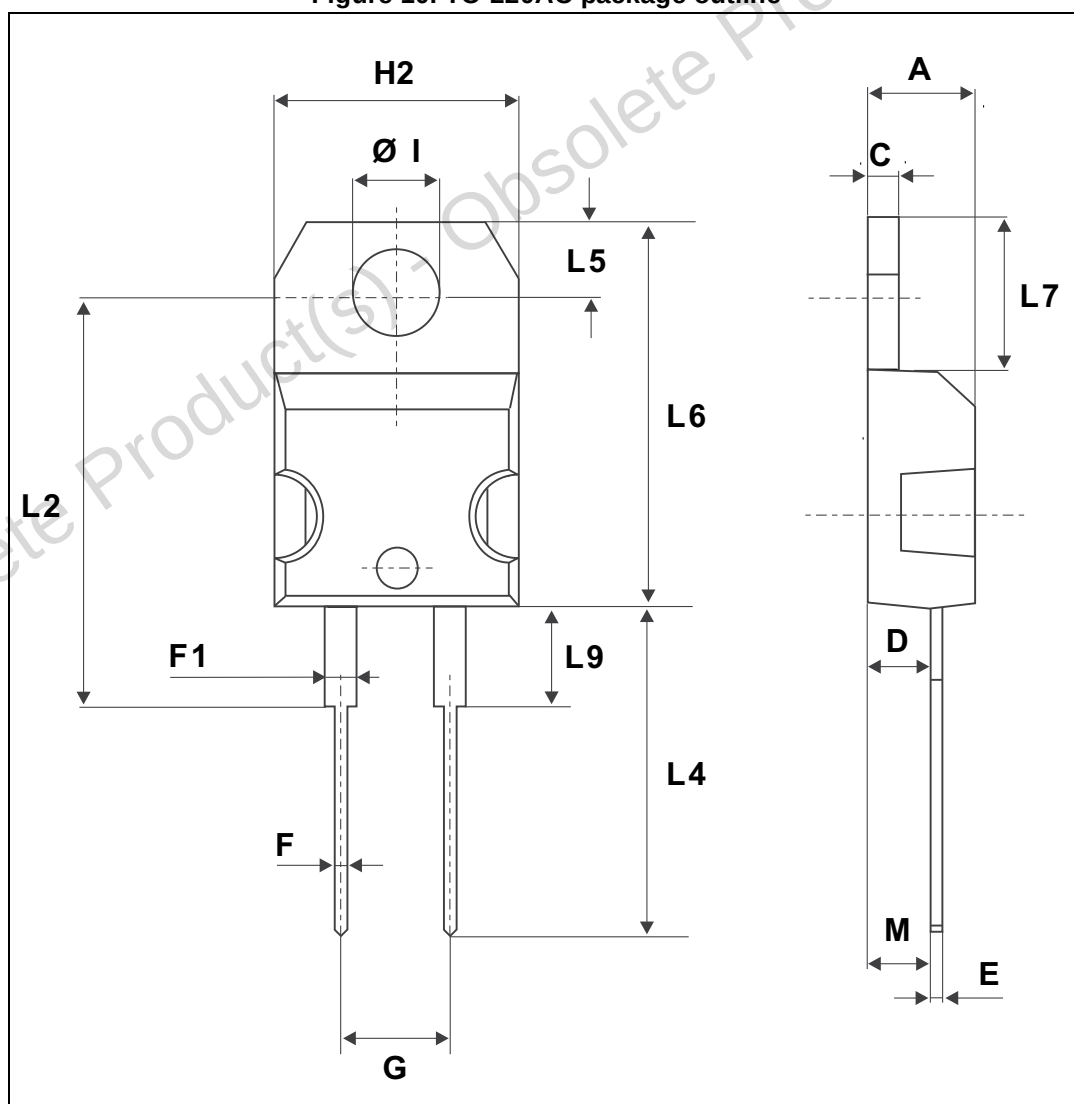


Table 5. TO-220AC package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
C	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
E	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.066
G	4.95		5.15	0.194		0.202
H2	10.00		10.40	0.393		0.409
L2		16.40 typ.			0.645 typ.	
L4	13.00		14.00	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.20		6.60	0.244		0.259
L9	3.50		3.93	0.137		0.154
M		2.6 typ.			0.102 typ.	
Diam. I	3.75		3.85	0.147		0.151

3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30M60D	STPS30M60D	TO-220AC	1.86 g	50	Tube

4 Revision history

Table 7. Document revision history

Date	Revision	Changes
25-Oct-2011	1	First issue.
23-Apr-2015	2	Updated Table 4 and reformatted to current standard.

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